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Rc: Our Docket No. 60702 (71987)
U.S. Serial No. 10/763,656

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Docket No. 60702 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang et al.

U.S. SERIAL NO.: 10/763,656

EXAMINER: T. Magee

FILED: January 23, 2004

GROUP: 2811

FOR: SEMICONDUCTOR PACKAGE WITH PHOTSENSITIVE CHIP
AND FABRICATION METHOD THEREOF**CERTIFICATE OF FACSIMILE TRANSMISSION**

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By: 

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Sir:

RESPONSE TO OFFICE ACTION

Applicants are in receipt of the Office Action dated November 15, 2004 of the above-referenced application. A request for a one-month extension of time is submitted herewith. Applicants respond to the Office Action as follows.

Claims 1-20 are pending in the subject application. Applicants appreciate the notification of allowable subject matter, i.e., that claims 15-20 are allowed.

Applicants' claimed invention is directed to a semiconductor package with a photosensitive chip and a fabrication method thereof. A substrate having a core is prepared, and a solder mask layer is applied over a surface of the core, the solder mask layer being formed with an opening to expose a peripheral portion on the surface of the core. At least one photosensitive